



제25회 한국반도체학술대회

The 25th Korean Conference on Semiconductors

2018년 2월 5일(월)-7일(수), 강원도 하이원리조트 컨벤션 호텔

2018년 2월 6일(화), 14:10-15:55

Room A (태백, 5층)

A. Interconnect & Package 분과

[TA2-A] FOWLP & Reliability

좌장: 김사라은경 교수(서울과학기술대학교), 이웅선 수석(SK 하이닉스)

<p>TA2-A-1 14:10-14:40</p>	<p>[초청] High-Density Fan-out Technology for Advanced 3D SiP and Heterogeneous Integration KangWook Lee <i>Global RnD, Amkor Technology Korea Inc.</i></p>
<p>TA2-A-2 14:40-14:55</p>	<p>Performance Comparisons between Thermocompression and Laser-Assisted Bonding for 3D Stacking Process Kwang-Seong Choi, Wagno Alves Braganca Junior, leeseul Jeong, Keon-Soo Jang, Seok Hwan Moon, Hyun-Cheol Bae, and Yong-Sung Eom <i>ICT Materials and Components Laboratory, ETRI</i></p>
<p>TA2-A-3 14:55-15:10</p>	<p>Analysis for Burnout Failure on Interconnect Metal Under High Current Stress Chang Hwi Lee, Jae Young You, Seong Bae Kim, Min Jae Hur, Sangho Won, Si Woo Lee, and Man Ho Seung <i>SK Hynix</i></p>
<p>TA2-A-4 15:10-15:25</p>	<p>3차원 반도체에서 테스트 발열을 고려한 테스트 스케줄링 기법 이예원, 이인걸, 정민호, 강성호 <i>Department of Electrical and Electronic Engineering, Yonsei University</i></p>
<p>TA2-A-5 15:25-15:40</p>	<p>Electrochemical Polishing of Cu Redistribution Layers for Fan Out Wafer Level Packaging Ki Moon Park¹, Jin Hyun Lee², and Bong Young Yoo^{1,2} <i>¹Department of Advanced Material Science & Engineering, Hanyang University, ²Department of Material Science & Engineering, Hanyang University</i></p>
<p>TA2-A-6 15:40-15:55</p>	<p>PCW 온도 제어를 통한 Cu CMP Removal Rate 변화 특성 연구 Jinhyung Lee, Yohan Jeon, Seong Sik Kim, Kyung-ho Hwang, and Sang Deok Kim <i>DRAM C&C, Process Center, SK Hynix</i></p>